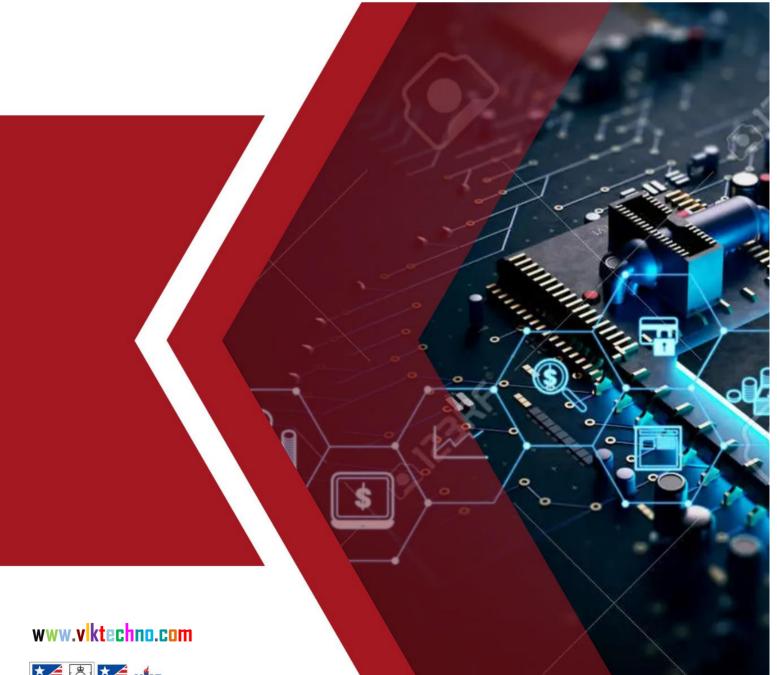


V.L.K. TECHNO TRADE CO., LTD.

Industrial Solutions

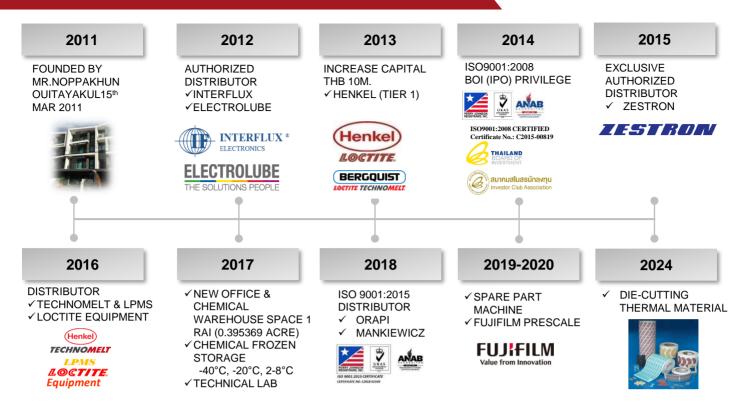








COMPANY HISTORY BOARD



	OUR SERVICE		
	BUFFER STOCK		
	SOURCING		
3	IMPORT DG LICENSE		
	FLEXIBLE & FAST DELIVERY		
5	FREEZER STORAGE 2-8°C / -20°C / -40°C		
	BOI PRIVILEGE		
7	DOWNLOAD CHIPBONDER		
8	DIE-CUTTING : THERMAL MATERIAL		



ELECTROLUBE	https://electrolube.com		
THE SOLUTIONS PEOPLE			
MAKE IT WITH A GLOBAL SOLUTIONS PROVIDER. ELECTROLUBE HAVE BEEN DEVELOPING SOLUTIONS TO ADVANCE ENGINEERING AND ENCHANCE TECHNOLOGICAL PERFORMANCE, SINCE 1941. WITH OUR EXPANSIVE RANGE OF PRODUCTS AND A COMMITMENT TO PUSH THE BOUNDARIES, THERE IS NO END TO THE APPLICATIONS OF ELECTROCHEMICAL SOLUTIONS.			
CONFORMAL COATINGS	MAINTENANCE & SERVICE AIDS		
ELECTRONIC & GENERAL CLEANING	THERMAL MANAGEMENT		
ENCAPSULATION RESINS	CONTACT LUBRICANTS		

Electronic & General	Conformal	Encapsulation	Contact	Maintenance
Purpose Cleaning	Coatings	Resins	Lubricants	& Service Aids

- * AUTOMOTIVE
- * MILITARY
- * AEROSPACE
- * TRANSPORT
- * MARINE
- * TELECOMMUNICATIONS
- * MEDICAL

- **CONSUMER ELECTRONICS**
- **INDUSTRIAL ELECTRONICS**
- * TRANSPORT
- **WITILITIES**
- **SERVICE, REPAIR AND MAINTENANCE**
- * LED



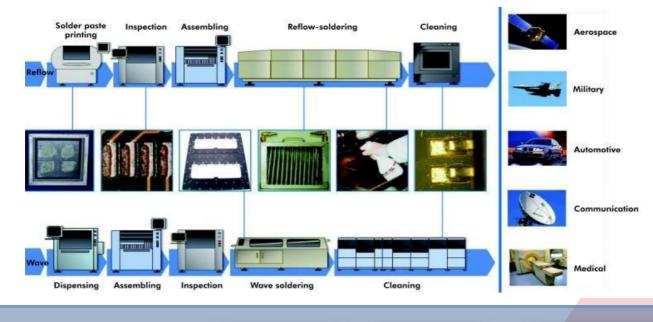


Bringing chemistry to electronics for over 42+ years.





A CLEANING SOLUTION FOR ANY APPLICATION



ECO-FRIENDLY SURFACE MOUNT TECHNOLOGY & THROUGH HOLE





PCB DEFLUXING CLEANING SOLUTIONS TO REMOVE FLUX RESIDUES



STENCIL & MISPRINT REMOVE SOLDER PASTE,



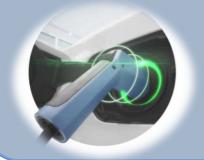
MAINTENANCE REMOVE BAKED-ON FLUX RESIDUE, ADHESIVES AND CONFORMAL COATING

SEMICONDUCTOR CLEANING **POWER ELECTRONICS,**

ADV.PACKAGING, WAFER



RISK PREVENTION HIGH VOLTAGE



♦ EXCEPTIONAL COMPATIBILITY

- ✤ HIGH WIRE BOND YIELD & RELIABILITY
- IMPROVED PRODUCTIVITY

POWER ELECTRONICS CLEANING

- ✓ POWER MODULES
- ✓ LEADFRAMES
- ✓ POWER LEDs

WAFER CLEANING

✓ OUR SOLUTIONS REDUCE CARBON **CONCENTRATIONS FROM 55% TO** 0.1%

PACKAGE CLEANING

- ✓ FLIP CHIPS
- ✓ CMOS *√*



E-MOBILITY & HIGH VOLTAGE CLEANING SOLUTIONS TO REMOVE FLUX RESIDUES







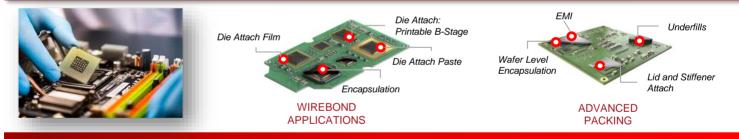
GLOBAL INNOVATION LEADER OF ELECTRONIC ASSEMBLY MATERIALS



CONSUMER ELECTRONICS : ADHESIVE SOLUTIONS FOR CONSUMER ELECTRONICS



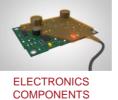
SEMICONDUCTOR PACKAGING : INNOVATIVE MATERIALS FOR EVOLUTIONARY ELECTRONICS CAPABILITY



INDUSTRIAL & INFRASTRUCTURE : POWER, AUTOMATING AND CONNECTING THE WORLD









LIGHTING



DATA & TELECOM INFRASTRUCTURE

SOLAR ENERGY : FACILITATING NEXT-GENERATION SOLAR TECHNOLOGIES WITH INNOVATIVE MATERIALS





POWER **GENERATION AND** CONVERSION



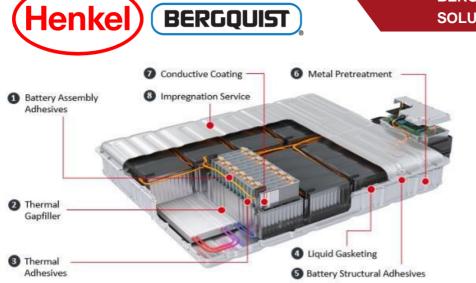
WIND ENERGY



ALTERNATIVE **ENERGY POWER** CONVERSION



Henkel





BERGQUIST THERMAL MANAGEMENT





Thermal Materials

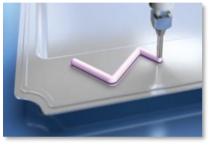
Thermal Substrates





Membrane Switches

Fans and Blowers



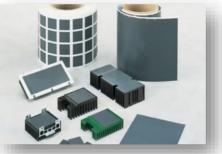
THERMAL GAP FILLERS THERMALLY CONDUCTIVE, LIQUID GAP FILLING MATERIALS



ADHESIVES HIGH STRUCTURAL IN SEVERE ENVIRONMENTS



THERMAL GAP PADS DESIGNED TO FILL AIR GAPS AND ENHANCE THERMAL CONDUCTIVITY



PHASE CHANGE MATERIALS PRE-APPLIED, DRY MATERIAL WITH BETTER LONG-TERM THERMAL PERFORMANCE AND LESS MESS THAN GREASE



SIL PADS ELECTRICALLY AND NON-ELECTRICALLY INSULATING



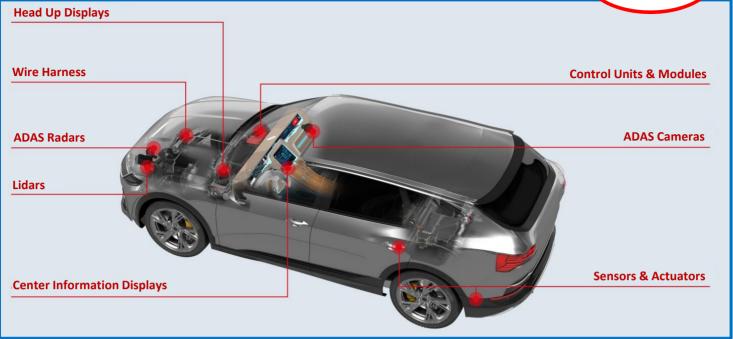
THERMALLY CONDUCTIVE GREASE ENSURING HIGH THERMAL TRANSFER ON AN INTERFACE,

COMPREHENSIVE SOLUTIONS FOR AUTOMOTIVE ELECTRONIC COMPONENTS



AUTOMOTIVE SOLUTION





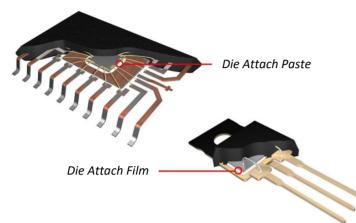




LEADFRAME SOLUTIONS

WIREBOND LEADFRAME SOLUTIONS :

Adhesive electronic solutions for leadframe, laminate and smart card



WAFER LEVEL ENCAPSULATION

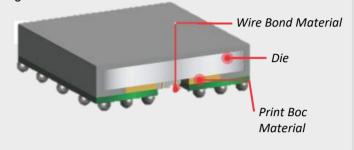
KEY BENEFITS OF HENKEL LCM

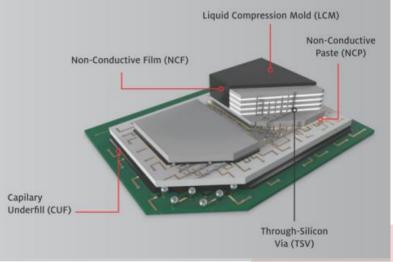
- · Low viscosity for easy flow and better fill
- · Better handling, no dust
- Ultra-low warpage, low CTE & low modulus for water handling & processing
- Low temperature and fast in-mold cure for increased UPH
- · EU REACH compliant anhydride-free

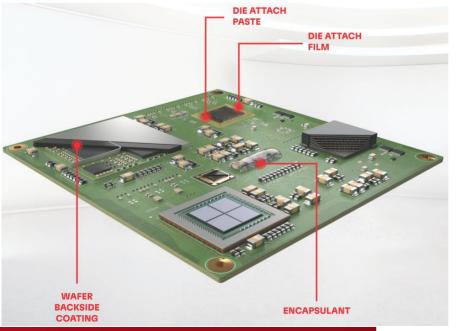
PRINTABLE BOC DIE ATTACH MATERIALS

Board-on-Chip (BoC) is a common chip-scale packing technique for memory devices, particularly DRAM. Because of the requirement for controlled tolerances and fine features, die attach materials must deliver key attributes like minimized die tilt, uniform bond line thickness, and little to no fillet formation.

Henkel has perfected B-stage printable adhesives that align with mass production dynamics and enable fine feature designs.





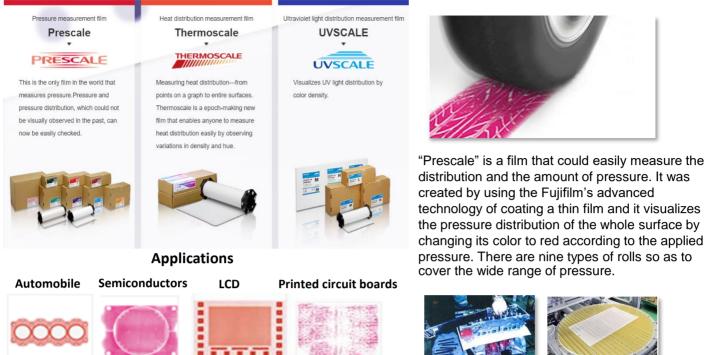


LAMINATE PACKAGING MATERIALS

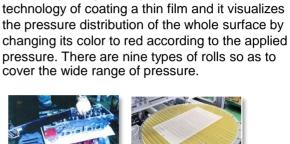
In addition to Henkel's well-known Bismaleimade (BMI)-based adhesives, new advances in IC packaging materials have been developed to facilitate high performance for various package designs – from LGAs to large format SiPs and SoMs. Products are available in paste, liquid, and film mediums, offering processing flexibility and precision for the most demanding applications and manufacturing environments.

Easily measuring pressure, heat and UV light with film.

FUJ!FILM Industrial



Pleated Cartridge Filter / Capsule Filter





Absolute Type

- Polysulfone membrane
- Lineup of pore sizes from 0.03um~1.2um
- Lineup series
- PSE-W, PSF, PSK, PSS03, PSE05, PSE-L, PSE-XL, PSE-UXL/SXL



Capsule filter

- Polysulfone membrane
- Pore size of 0.1~0.45um
- Lineup series :
- **PSE** Capsule .



Nominal Type

- Polyproplyene membrane
- Lineup of pore sizes from 0.4um~30um
- Lineup series :
- PPE. PPE-UXL

SMT SPARE PARTS

- **Panasonic**
 - SIEMENS

HITACHI

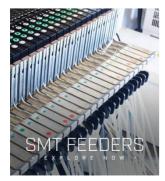
JUKI



Assembleon



(UniversaL









SAMSUNG

Dek

V.L.K. WAREHOUSE & STORAGE SYSTEM

- > AIR CONDITION CONTROL
- > 25°C (± 3°C)
- > OPEN AIR CONDITION 24 HOURS > ALARM SYSTEM
- HUMIDITY 40-70
- FIFO CONTROL
- FLAMABLE STORAGE ROOM
- BATTERY BACKUP
- > GENERATOR
- ALARM SYSTEM (VOICE/SMS ALARM)
- > TEMP DATA LOGGER : REAL TIME RECORD TEMP MONITORING.





LINE Notify \cap Freezer (VLK): Line Group 1 Name : R1 (-40°c) Status : TURNED TO NORMAL. NORMAL. Temperature : -44.7 °C Set (Max/Min) : -35.0/-45.0 °C Time : 14:29:15 21/05/2024. LINE Notify LINE Notify Freezer (VLK): Line Group 1 Name : R1 (-40°c) Status : TURNED TO NORMAL. POE LAN SWITCH NORMAL. Temperature : -44.7 °C Set (Max/Min) : -35.0/-45.0 °C Time : 16:10:14 21/05/2024. -----ADSL MODEM ---------UTP CABLE REMOTE PC Wifi UTP CABLE POE FREEZER MONITOR MODULE CLIENT PC ALARM SMS GSM MODEM SERVER

V.L.K. DIE-CUTTING



TOTAL SOLUTION IN THERMAL MANAGEMENT

- Available in custom sheets and die-cut shapes.
- V.L.K.. stocks and sources a variety of materials for die cut thermal gap pads.

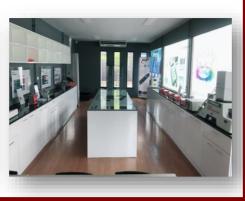


We offer customized solutions to meet our customers' needs.

We can make follow customer designed.

V.L.K. TECHNICAL LAB







TECHNICAL LAB FOR TEST



FREE SUPPORT

DOWNLOAD ADHESIVE TO SERVE VARIOUS PACKAGE SIZE



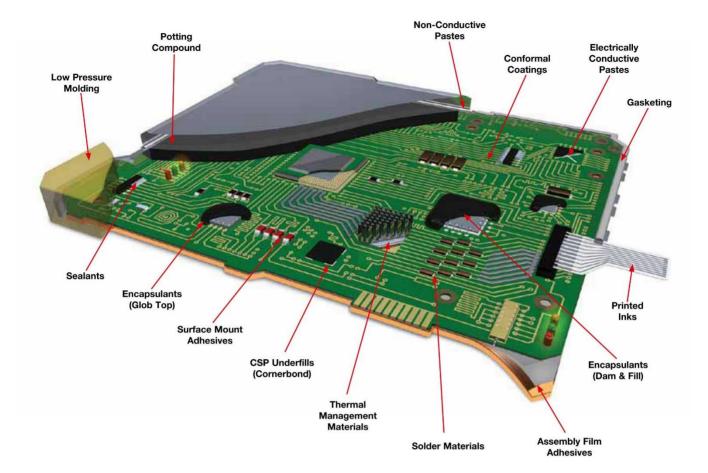








NOTED



Line@



149049



Website



Address :

36/7 Moo 13, Bungkumploy Sub-District, Lam Luk Ka District, Pathumthani 12150

Telephone No. : +66 2-150-0247-51 Fax : +66 2-150-0252 Mobile :+66 81-430-1551

Contact us :

sales@vlk.th.com

- https://www.vlktechno.com
- 👎 V.L.K. Techno trade co., Itd.
- 🡳 @vlktechnotrade